# **Power MOSFET**

# 72 A, 25 V, N-Channel DPAK

#### **Features**

- Planar HD3e Process for Fast Switching Performance
- Low R<sub>DS(on)</sub> to Minimize Conduction Loss
- Low C<sub>ISS</sub> to Minimize Driver Loss
- Low Gate Charge
- Pb-Free Packages are Available

## MAXIMUM RATINGS (T<sub>J</sub> = 25°C Unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	25	$V_{dc}$
Gate-to-Source Voltage - Continuous	V <sub>GS</sub>	±20	$V_{dc}$
Thermal Resistance – Junction-to-Case Total Power Dissipation @ T <sub>C</sub> = 25°C Drain Current	$R_{ heta JC} P_D$	2.4 62.5	°C/W W
$ \begin{array}{lll} - \mbox{ Continuous } @\ T_C = 25^{\circ}\mbox{C}, \mbox{ Chip} \\ - \mbox{ Continuous } @\ T_C = 25^{\circ}\mbox{C}, \mbox{ Limited by Package} \\ - \mbox{ Continuous } @\ T_A = 25^{\circ}\mbox{C}, \mbox{ Limited by Wires} \\ - \mbox{ Single Pulse } (t_p = 10\ \mu\text{s}) \end{array} $	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	72.0 62.8 32 140	A A A
Thermal Resistance – Junction-to-Ambient (Note1)	$R_{\theta JA}$	80	°C/W
Total Power Dissipation @ T <sub>A</sub> = 25°C Drain Current - Continuous @ T <sub>A</sub> = 25°C	$P_{D}$	1.87 12.0	W A
Thermal Resistance – Junction-to-Ambient (Note2)	$R_{\theta JA}$	110	°C/W
Total Power Dissipation @ T <sub>A</sub> = 25°C Drain Current - Continuous @ T <sub>A</sub> = 25°C	$P_{D}$	1.36 10.0	W A
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ( $V_{DD} = 30 \ V_{dc}, \ V_{GS} = 10 \ V_{dc}, \ I_L = 12 \ A_{pk}, \ L = 1 \ mH, \ R_G = 25 \ \Omega)$	E <sub>AS</sub>	71.7	mJ
Maximum Lead Temperature for Soldering Purposes, 1/8" from Case for 10 s	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

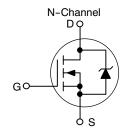
- 1. When surface mounted to an FR4 board using 0.5 sq. in. pad size.
- 2. When surface mounted to an FR4 board using minimum recommended pad size.



# ON Semiconductor®

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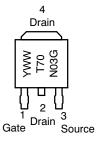
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX
25 V	$5.6~\text{m}\Omega$	72 A

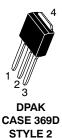


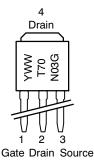
#### **MARKING DIAGRAMS**



CASE 369AA STYLE 2







70N03 = Device Code = Year WW = Work Week = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ Unless otherwise specified)

C	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS		•		•	•	-1
Drain-to-Source Breakdown ( $V_{GS}$ = 0 $V_{dc}$ , $I_D$ = 250 $\mu$ A Temperature Coefficient (Pos	V <sub>(br)DSS</sub>	25 -	28 20.5	- -	V <sub>dc</sub> mV/°C	
Zero Gate Voltage Drain Curr $(V_{DS} = 20 V_{dc}, V_{GS} = 0 V_{dc}, V_{GS} = 0 V_{dc})$	I <sub>DSS</sub>	- -	- -	1.5 10	μA <sub>dc</sub>	
Gate-Body Leakage Current $(V_{GS} = \pm 20 V_{dc}, V_{DS} = 0 V_{dc})$		I <sub>GSS</sub>	1	-	±100	nA <sub>dc</sub>
ON CHARACTERISTICS (No	ote 3)					
Gate Threshold Voltage (Note ( $V_{DS} = V_{GS}$ , $I_D = 250 \mu A_d$ Threshold Temperature Coef	c) <sup>'</sup>	V <sub>GS(th)</sub>	1.0 -	1.5 4.0	2.0	V <sub>dc</sub> mV/°C
Static Drain-to-Source On-F ( $V_{GS} = 4.5 V_{dc}$ , $I_D = 20 A_c$ ( $V_{GS} = 10 V_{dc}$ , $I_D = 20 A_d$	dc)	R <sub>DS(on)</sub>	- -	8.1 5.6	13 8.0	mΩ
Forward Transconductance ( $V_{DS} = 10 V_{dc}$ , $I_D = 15 A_{dc}$		9FS	1	27	-	Mhos
DYNAMIC CHARACTERISTI	cs					
Input Capacitance		C <sub>ISS</sub>	-	1333	-	pF
Output Capacitance	$(V_{DS} = 20 V_{dc}, V_{GS} = 0 V,$ f = 1 MHz)	C <sub>OSS</sub>	-	600	-	
Transfer Capacitance	,	C <sub>RSS</sub>	1	218	-	
SWITCHING CHARACTERIS	STICS (Note 4)					
Turn-On Delay Time		t <sub>d(on)</sub>	-	6.9	-	ns
Rise Time	$(V_{GS} = 10 V_{dc}, V_{DD} = 10 V_{dc},$	t <sub>r</sub>	-	1.3	-	
Turn-Off Delay Time	$I_D = 36 A_{dc}, R_G = 3 \Omega$	t <sub>d(off)</sub>	-	18.4	-	
Fall Time	1	t <sub>f</sub>	-	5.5	-	1
Gate Charge		Q <sub>T</sub>	-	13.2	-	nC
	$(V_{GS} = 5 V_{dc}, I_D = 36 A_{dc}, V_{DS} = 10 V_{dc})$ (Note 3)	Q <sub>GS</sub> - 3.3 -		-		
	3 40, ( 333 3,	Q <sub>DS</sub>	1	6.5	-	
SOURCE-DRAIN DIODE CH	IARACTERISTICS					
Forward On-Voltage	$(I_S = 20 \text{ A}_{dc}, \text{ V}_{GS} = 0 \text{ V}_{dc}) \text{ (Note 3)}$ $(I_S = 20 \text{ A}_{dc}, \text{ V}_{GS} = 0 \text{ V}_{dc}, \text{ T}_J = 125^{\circ}\text{C})$	V <sub>SD</sub>	- -	0.86 0.73	1.2 -	V <sub>dc</sub>
Reverse Recovery Time		t <sub>rr</sub>	-	27.9	-	ns
	# aa.k .v. a.v.	t <sub>a</sub>	-	14.8	-	7
	$(I_S = 36 A_{dc}, V_{GS} = 0 V_{dc}, \\ dI_S/dt = 100 A/\mu s) (Note 3)$		-	13.1	-	7
Reverse Recovery Stored Charge		Q <sub>RR</sub>	-	19	-	nC

Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2%.
 Switching characteristics are independent of operating junction temperatures.

# TYPICAL PERFORMANCE CURVES ( $T_J = 25^{\circ}C$ unless otherwise noted)

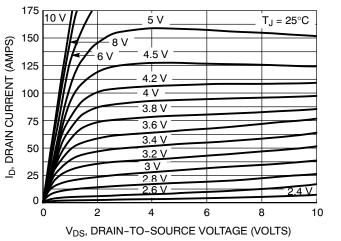
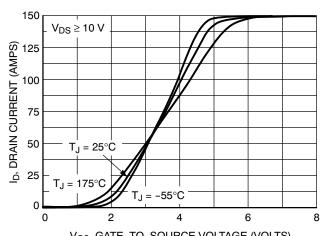


Figure 1. On-Region Characteristics



V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 2. Transfer Characteristics

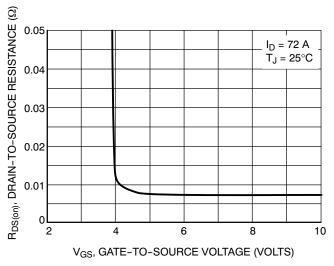


Figure 3. On-Resistance versus Gate-to-Source Voltage

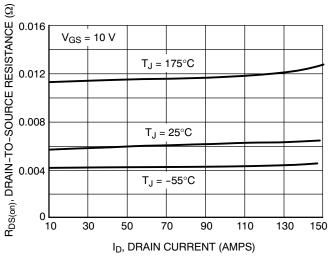


Figure 4. On-Resistance versus Drain Current and Gate Voltage

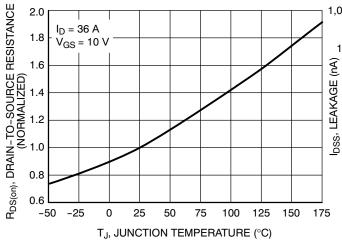


Figure 5. On-Resistance Variation with Temperature

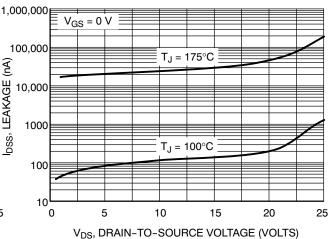
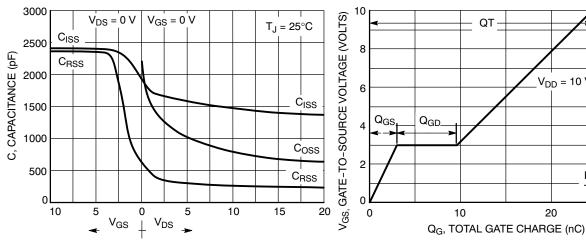


Figure 6. Drain-to-Source Leakage Current versus Voltage



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

Figure 8. Gate-To-Source and Drain-To-Source Voltage versus Total Charge

V<sub>DD</sub> = 10 V

I<sub>D</sub> = 36 A  $T_J = 25^{\circ}C$ 

30

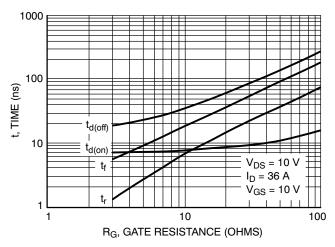


Figure 9. Resistive Switching Time Variation versus Gate Resistance

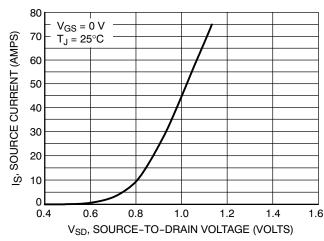


Figure 10. Diode Forward Voltage versus Current

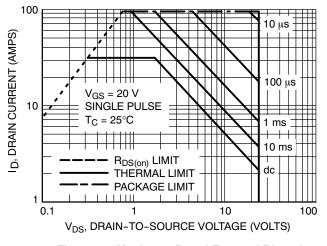


Figure 11. Maximum Rated Forward Biased Safe Operating Area

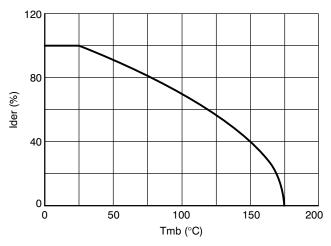


Figure 12. Normalized Continuous Drain Current as a function of Mounting Base Temperature

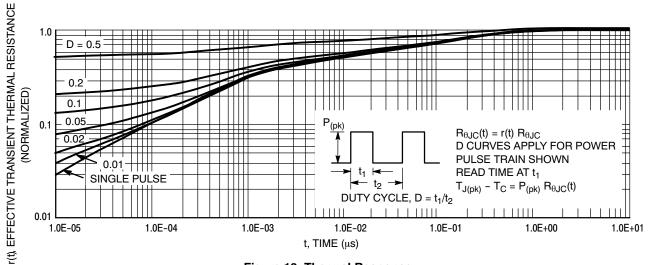


Figure 13. Thermal Response

### **ORDERING INFORMATION**

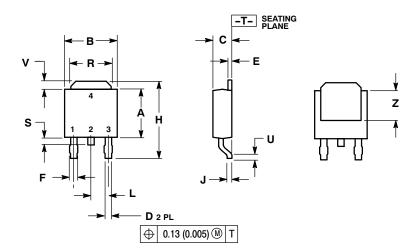
Order Number	Package	Shipping $^{\dagger}$	
NTD70N03R	DPAK-3	75 Units / Rail	
NTD70N03RG	DPAK-3 (Pb-Free)	75 Units / Rail	
NTD70N03RT4	DPAK-3	2500 / Tape & Reel	
NTD70N03RT4G	DPAK-3 (Pb-Free)	2500 / Tape & Reel	
NTD70N03R-1	DPAK-3 Straight Lead	75 Units / Rail	
NTD70N03R-1G	DPAK-3 Straight Lead (Pb-Free)	75 Units / Rail	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **PACKAGE DIMENSIONS**

#### **DPAK**

CASE 369AA-01 **ISSUE A** 

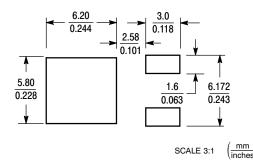


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		<b>MILLIMETERS</b>		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.22	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.025	0.035	0.63	0.89	
E	0.018	0.024	0.46	0.61	
F	0.030	0.045	0.77	1.14	
Н	0.386	0.410	9.80	10.40	
J	0.018	0.023	0.46	0.58	
L	0.090	BSC	2.29	BSC	
R	0.180	0.215	4.57	5.45	
S	0.024	0.040	0.60	1.01	
U	0.020		0.51		
V	0.035	0.050	0.89	1.27	
Z	0 155		3.93		

- STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

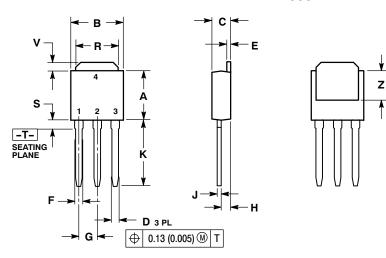
# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### **DPAK** CASE 369D-01 ISSUE B



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.35	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
E	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.090 BSC		2.29 BSC		
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
K	0.350	0.380	8.89	9.65	
R	0.180	0.215	4.45	5.45	
S	0.025	0.040	0.63	1.01	
V	0.035	0.050	0.89	1.27	
Z	0.155		3.93		

STYLE 2: PIN 1. GATE

- 2 DRAIN
- SOURCE DRAIN

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